

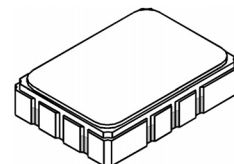
- *Designed for SDARS IF Receiver*
- *Low Insertion Loss*
- *5.0 X 7.0 mm Surface-Mount Case*
- *Differential or Single Ended Input and Output*

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range (with tape & reel)	-40 to +85	°C
Storage Temperature Range (without tape & reel)	-50 to +125	°C
Max Soldering Profile	265°C for 10 s	

SF2037B-2

**76.500 MHz
SAW Filter**



SMP-03

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_c	1		76.500		MHz
Passband Insertion Loss	IL			10.0	12.5	dB
1dB Passband	BW ₁		3.8	4.1		MHz
15dB Bandwidth	BW ₁₅			6.7	6.8	MHz
30dB Bandwidth	BW ₃₀			7.7	7.8	MHz
Amplitude Ripple over $f_c \pm 1.9$ MHz				0.5	1.10	dB _{p-p}
Group Delay Variation over $f_c \pm 1.9$ MHz	GDV			65	150	ns _{p-p}
Rejection						
50 to 70.44 MHz			37	43		
70.44 to 72.04 MHz			34	43		
81.26 to 82.56 MHz			38	49		
82.56 to 86.50 MHz			39	48		
86.5 to 91.50 MHz			41	48		
91.50 to 100.000 MHz			45	58		
Operating Temperature Range	T _A	1	-40		+105	°C
Frequency Temperature Coefficient	FTC			-18		ppm/°C
Differential Input			175 ohms			
Differential Output			1000 ohms			
Case Style			SMP-03 7 x 5 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			RFM SF2037B-2 YYWWS			

Electrical Connections

Connection	Terminals
Port 1 Hot	10
Port 1 Ground Return	1
Port 2 Hot	5
Port 2 Ground Return	6
Case Ground	All Others



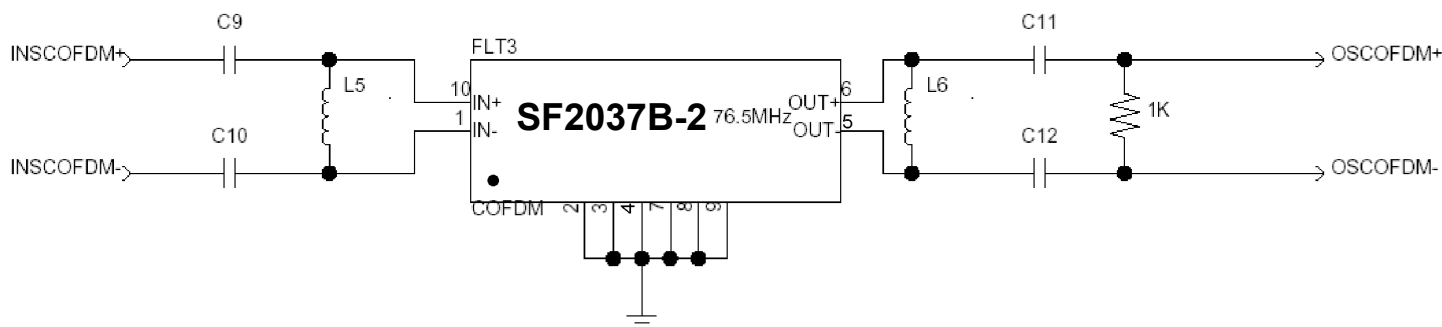
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

Matching Circuit and Matching Component Values Used in G3 Sirius Radios

(Refer to Sirius Radio G3 Chipset Application Note, Doc. #RX000104-B, Sec. 4.2.4)

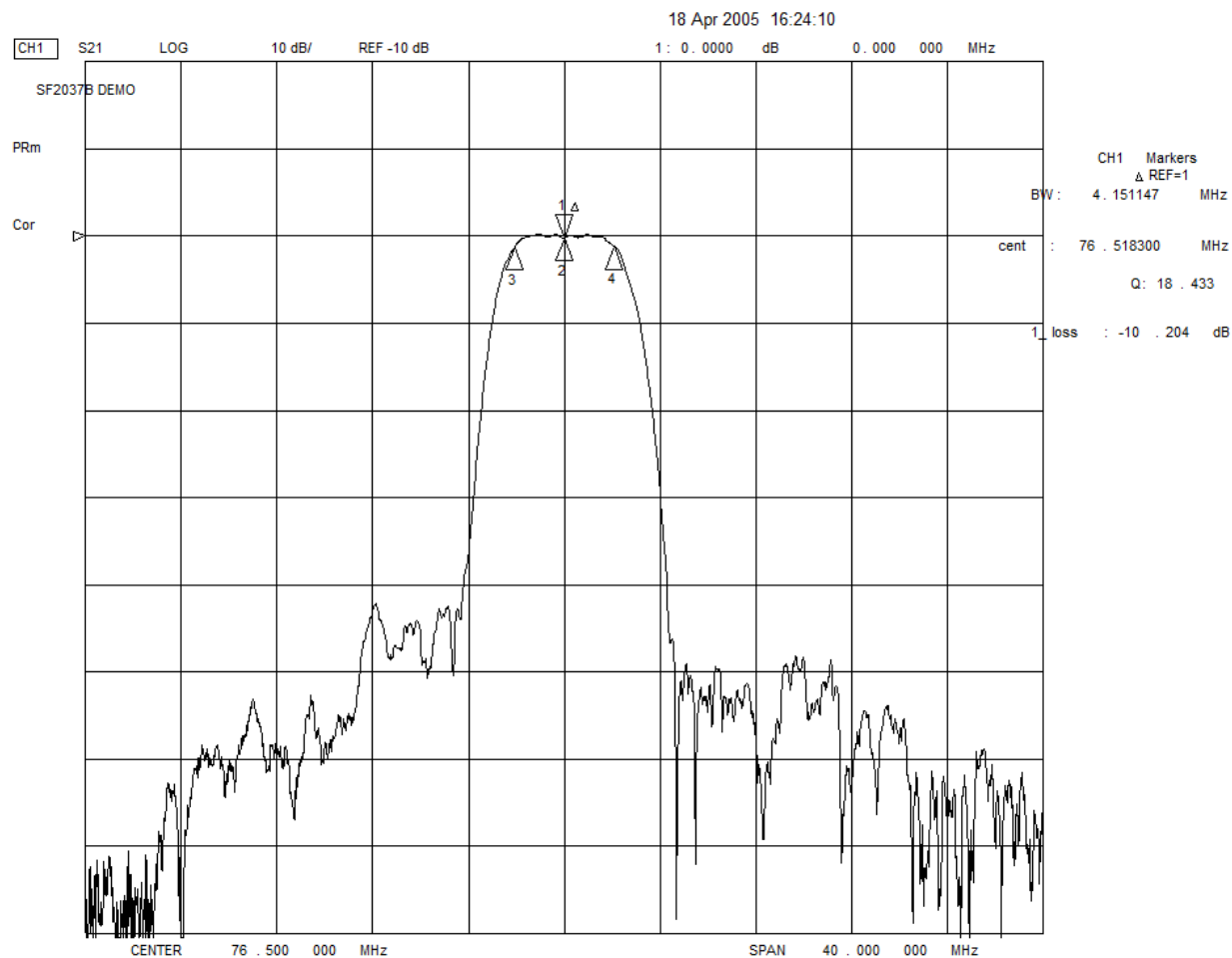
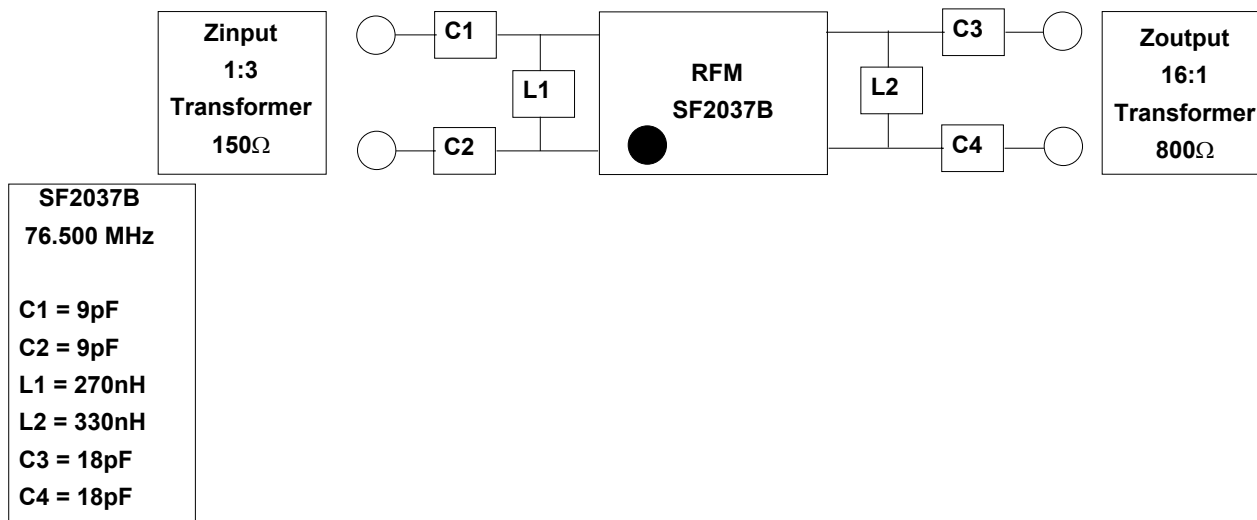


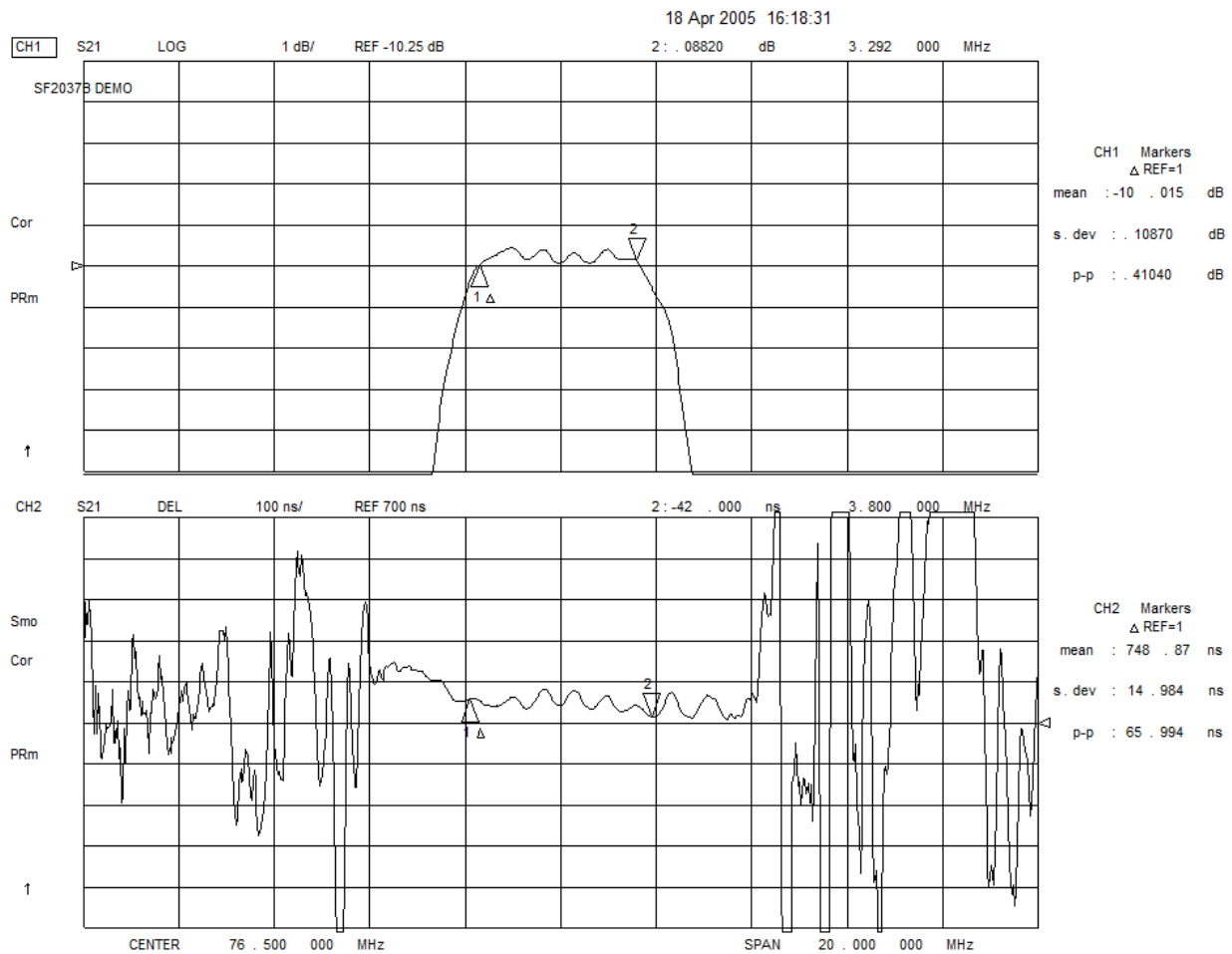
COFDM Narrowband SAW Matching Circuit

COFDM Narrowband SAW Matching Values

Reference Designator	Value
C9	10 pF
C10	10 pF
L5	270 nH
L6	390 nH
C11	100 pF
C12	100 pF

Matching Circuit and Matching Component Values Used on Filter Demo Board

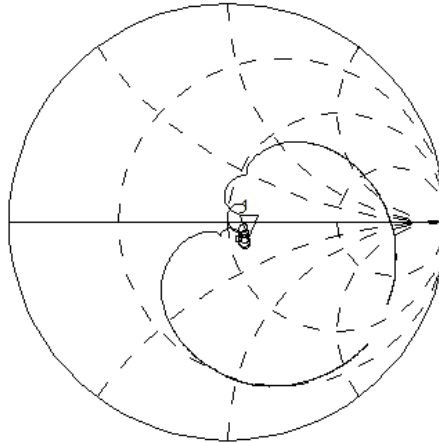




18 Apr 2005 16:28:43
 CH1 S11 1 UFS 1: 59.928 Ω -9.8086 Ω 212.11 pF 76.500 000 MHz
 SF2037B DEMO

Cor

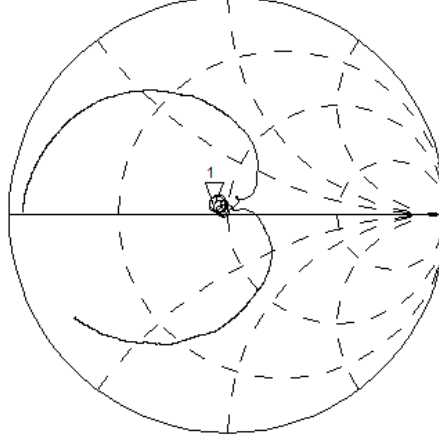
PRm



CH2 S22 1 UFS 1: 43.949 Ω 3.1992 Ω 6.6558 nH 76.500 000 MHz

Cor

PRm



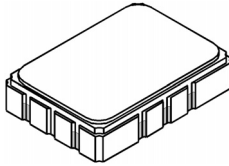
CENTER 76.500 000 MHz

SPAN 40.000 000 MHz

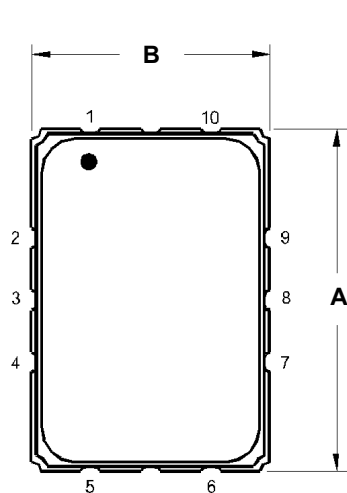
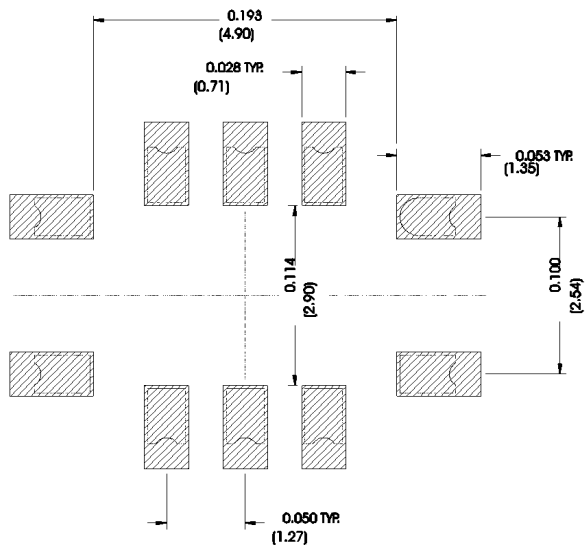
SMP-03 Case

10-Terminal Ceramic Surface-Mount Case

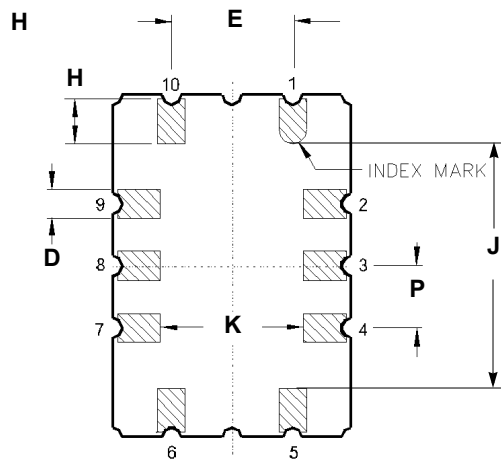
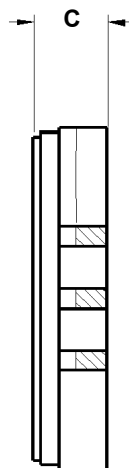
7 x 5 mm Nominal Footprint



Recommended PCB Footprint



TOP VIEW



BOTTOM VIEW

Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials

Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

Electrical Connections

Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot

Technical drawing of a circular part, likely a flange or end view of a pipe. The drawing includes three views:

- Top View:** A large circle with a smaller concentric circle in the center. A crosshair indicates the center. A dimension line points from the center to the text "See Detail 'A'".
- Side View:** A vertical cross-section showing the thickness of the part. The total thickness is dimensioned as 16.0. The inner hole is dimensioned as 100 REF. The outer diameter is dimensioned as "B" REF.
- Detail View:** A circular detail view showing the inner hole and the outer edge. The inner hole diameter is 13.0. The outer diameter is 20.2. The thickness of the flange is 2.0.

Product Reflow/ESD/MSL

Reflow Peak Temperature	265	°C
Reflow Peak Time	10	Seconds
Liquidus 217 Temperature/Time	110	Seconds
Over Liquidus 230 Temperature/Time	70	Seconds
Reflow Condition	SMT	
Class Level HBM	2	
HBM(V)	2000	HBM(V)
MM(V)	N/A	MM(V)
CDM(V)	2000	CDM(V)
MSL	1	

Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm

